

Dan Ionut Simă³n

List of Publications by Year in descending order

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11
papers

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citations

1937685

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1720034

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g-index

11
all docs

11
docs citations

11
times ranked

39
citing authors

#	ARTICLE	IF	CITATIONS
1	Reliability Analysis for Power Devices Which Undergo Fast Thermal Cycling. IEEE Transactions on Device and Materials Reliability, 2016, 16, 336-344.	2.0	27
2	A simple metal-semiconductor substructure for the advanced thermo-mechanical numerical modeling of the power integrated circuits. Microelectronics Reliability, 2018, 87, 142-150.	1.7	8
3	Measurement and investigation of thermal properties of the on-chip metallization for integrated power technologies. , 2013, , .		7
4	Influence of the On-Chip Metallization on Self-Heating in Integrated Power Technologies. IEEE Transactions on Semiconductor Manufacturing, 2014, 27, 169-177.	1.7	6
5	Experimental Reliability Improvement of Power Devices Operated Under Fast Thermal Cycling. IEEE Electron Device Letters, 2015, 36, 696-698.	3.9	6
6	Design and Operation of an Integrated High-Temperature Measurement Structure. IEEE Transactions on Semiconductor Manufacturing, 2012, 25, 542-548.	1.7	4
7	High temperature on-wafer measurement structure for DMOS characterization. , 2011, , .		3
8	A Novel Multi-Scale Method for Thermo-Mechanical Simulation of Power Integrated Circuits. IEEE Journal of the Electron Devices Society, 2022, 10, 169-179.	2.1	2
9	Modeling of a DMOS transistor up to very high temperatures. , 2011, , .		1
10	Reliability characterization of power devices which operate under power cycling. , 2015, , .		1
11	A Simple Metal-Semiconductor Substructure Model for the Thermal Induced Fatigue Simulation in Power Integrated Circuits. Lecture Notes in Mechanical Engineering, 2019, , 21-36.	0.4	1